



## JOCHC15B-D8P/S Series

Rev.A.1.0

The products are 15MBd high-speed opto-couplers in a plastic DIP8 package with different lead forming options. The device consists of a 850 nm AlGaAs LED, optically coupled to a very high speed integrated photo-detector logic gate with a strobable output. The output end of the product is a CMOS output, and the product has a strong common mode rejection capability. The coupled parameters are guaranteed over the temperature range of -40°C to +110°C. The products are widely used in communication interface, digital isolation for A/D, D/A conversion, high-voltage power systems, renewable energy inverters, medical imaging and patient monitoring.

- High isolation 5000 VRMS
- High speed – 15MBd typical
- Operating temperature range -40°C to 110°C
- REACH & RoHS compliance
- HBM: H3A; MM: M4; CDM: C3
- CQC approved
- VDE approved
- UL approved

LED	Output
ON	L
OFF	H

(Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I <sub>F</sub>	50	mA
	Peak Forward Current	I <sub>FP</sub>	1	A
	Reverse Voltage	V <sub>R</sub>	6	V

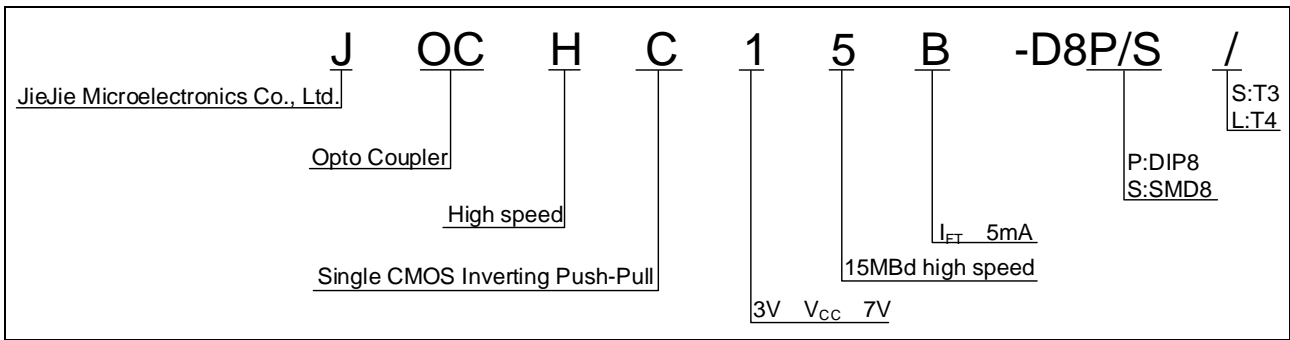
	Input Power Dissipation	$P_D$	100	mW
Output	Supply Voltage	$V_{CC}$	7	V
	Output Voltage	$V_O$	$V_{CC}+0.5$	V
	Output Current	$I_O$	10	mA
	Output Power Dissipation	$P_O$	22	mW
Total Power Dissipation		$P_{tot}$	130	mW
Isolation Voltage		$V_{iso}$	5000	Vrms
Operating Temperature		$T_{opr}$	-40~110	
Junction Temperature		$T_j$	125	
Storage Temperature		$T_{stg}$	-55~125	
Soldering Temperature		$T_{sol}$	260	

: 100 $\mu$ s pulse, 100Hz frequency

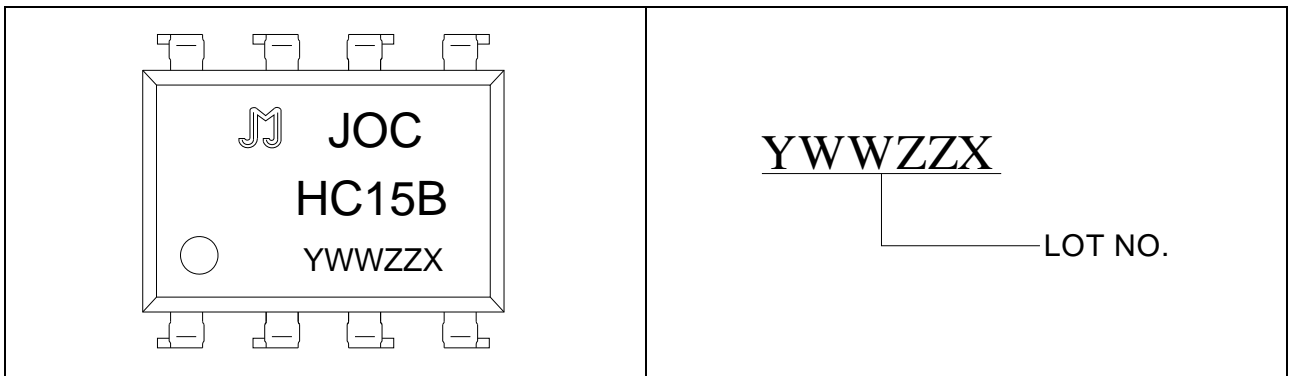
: AC for 1minute, R.H.=40~60%

(Temperature=25°C)





DIP	0Units/Tube
SMD	1200Units/Reel

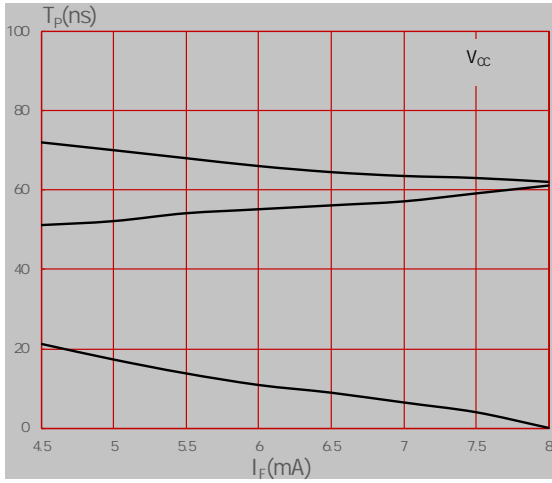


**FIG.1:** Forward Current vs. Forward Voltage



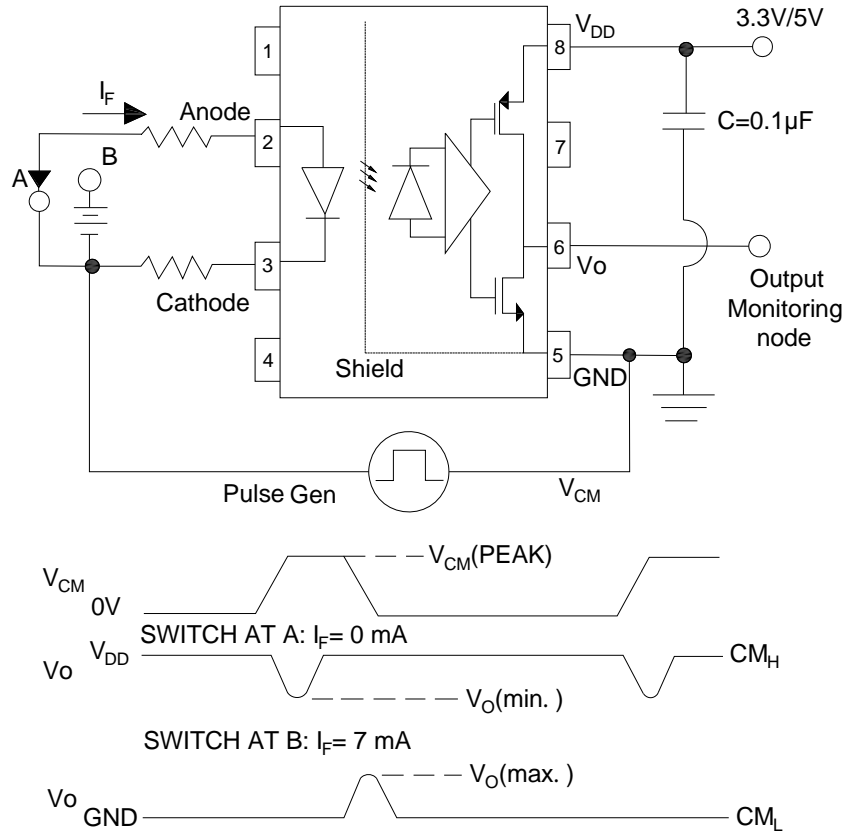
**FIG.2:** Max. Allowable LED Forward Current vs. Ambient Temperature

**FIG.7:** Propagation Delay vs. Ambient Temperature



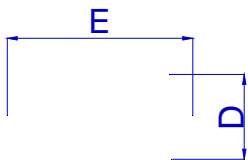
**FIG.8:** Propagation Delay vs. Ambient Temperature

Fig.10: CMTI Test Circuit Recommendations

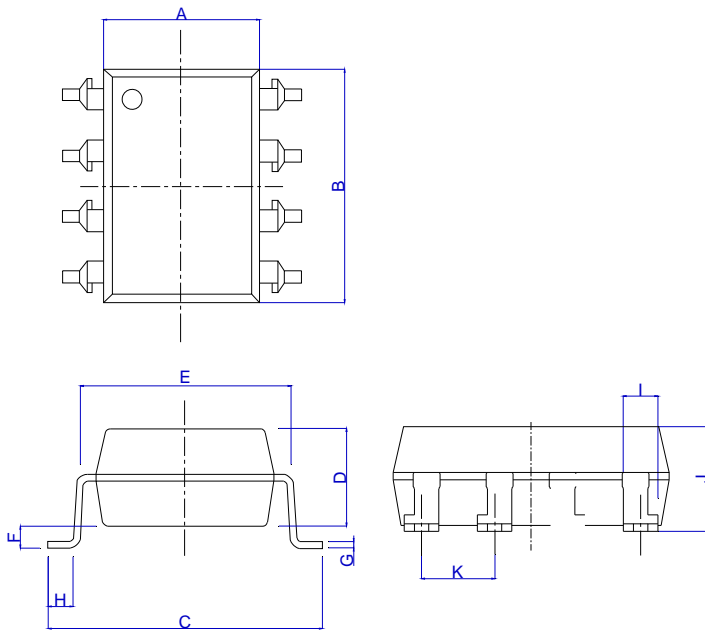


Standard DIP Type:

Dimensions  
 Millimeters      Inches

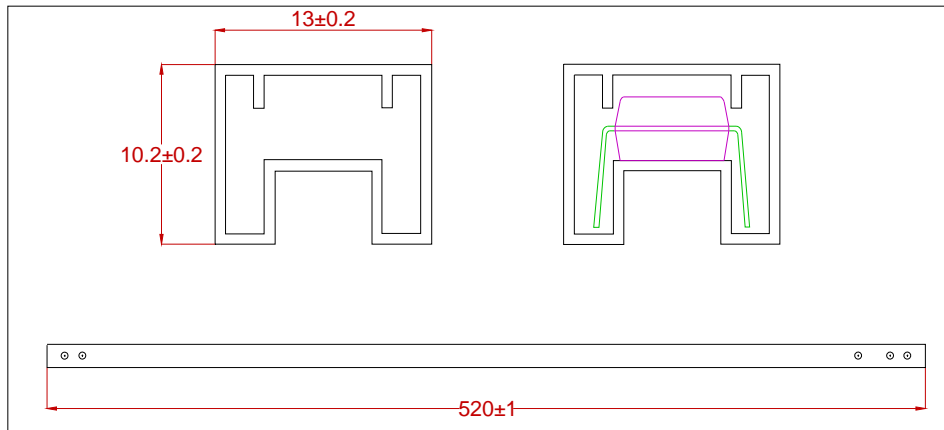


Option SMD Type:

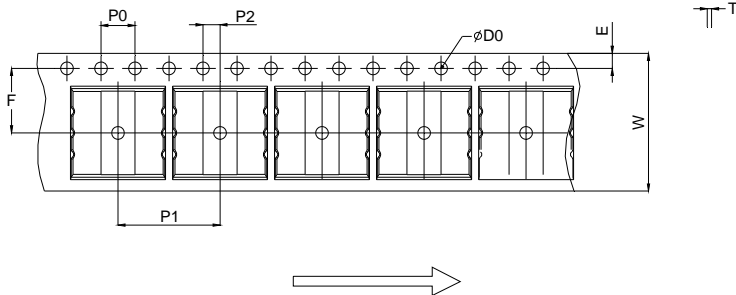


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

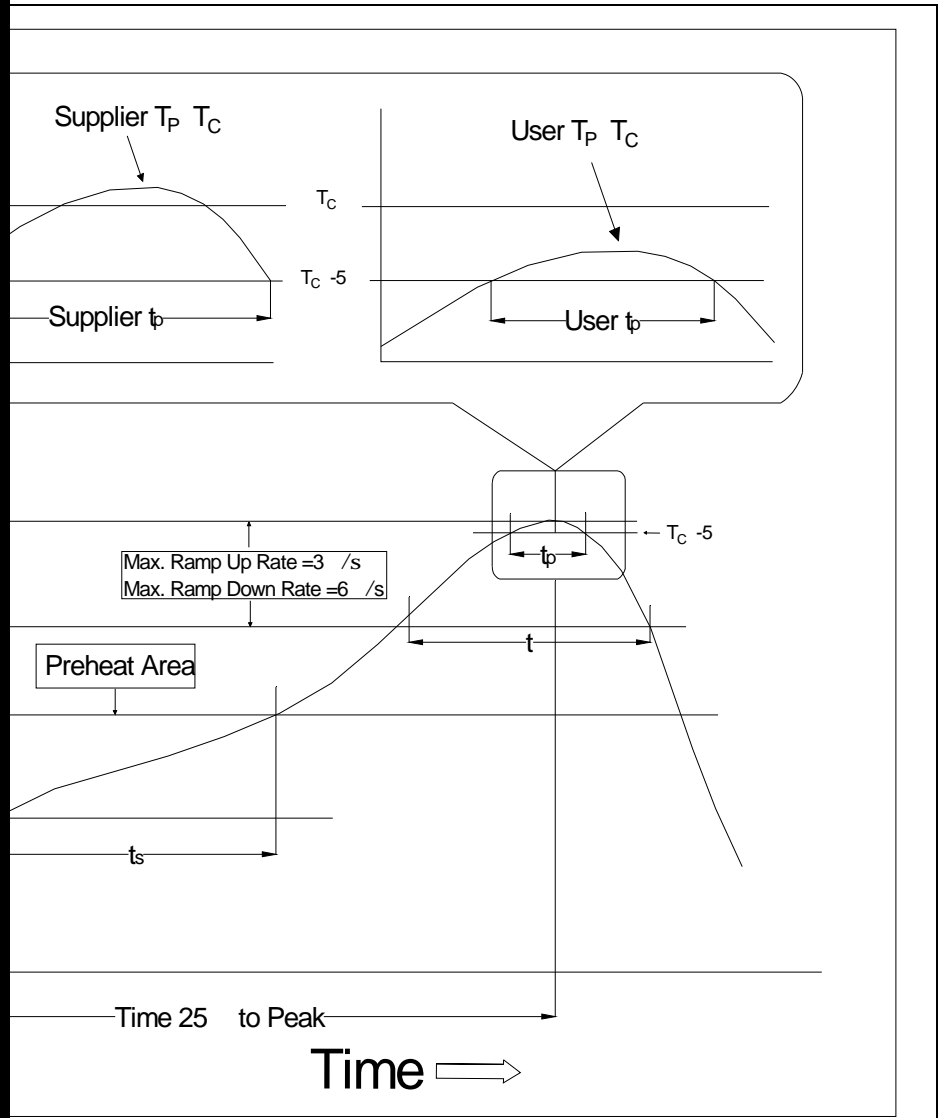
Standard DIP



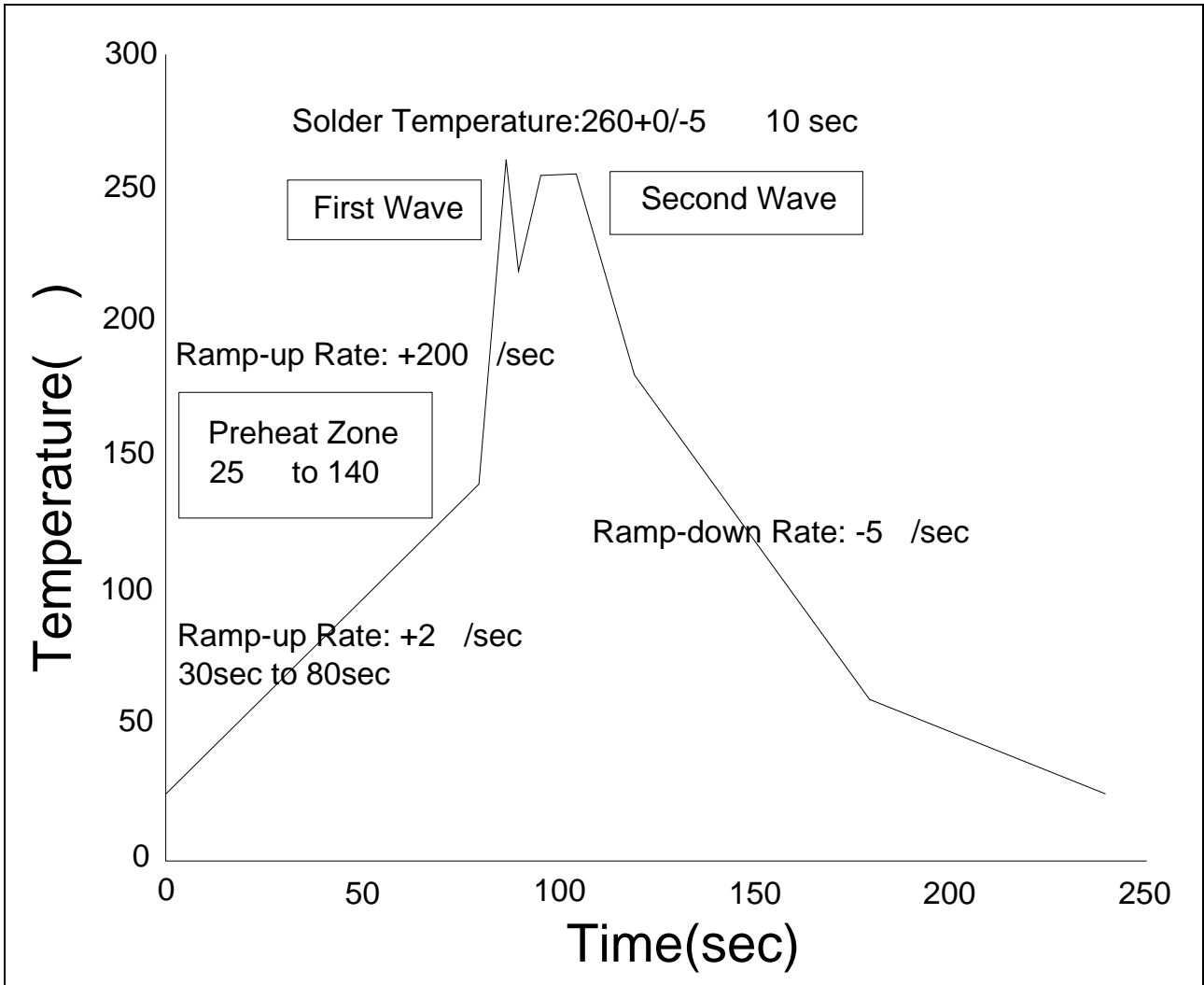
Option S/L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638



	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
(min)	100	150
(max)	150	200
(smax)	60-120 seconds	60-120 seconds
(P)	3 /second max.	3 /second max.
(TL)	183	217
ve (TL)	60-150 seconds	60-150 seconds




Soldering Temperature	$360 \pm 5$
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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